

ABSTRACT OF THE DISCLOSURE

A sacrificial layer is formed in a recess of a substrate, and leads extending from the substrate into an area of the sacrificial layer are formed. A cut is formed from the bottom surface of the substrate, the cut extending from the bottom surface to the area of the sacrificial layer via the substrate, then the sacrificial layer is removed. A probe unit can be obtained having the leads whose front portions extend beyond the edge of the substrate. A through conductor may be formed in a through hole formed in a substrate. Leads may be formed on a photosensitive etching glass substrate to thereafter selectively etch the chemically cutting type glass.